

KNOWN GOOD DIE REMOVAL METHOD AND APPARATUS

Abstract

A method and apparatus for separating a semiconductor device from a substrate in a fixture with a shearing element, wherein the semiconductor device is attached to the substrate by solder connections to form an assembly, includes using the shearing element to apply a loading force to the semiconductor device. The assembly of the substrate and the semiconductor device are loaded into the fixture with the shearing element proximate the semiconductor device, and heating the solder connections of the assembly in the fixture are heated proximate the substrate to a predetermined temperature by applying a heat source to a surface of the substrate distal from the semiconductor device.